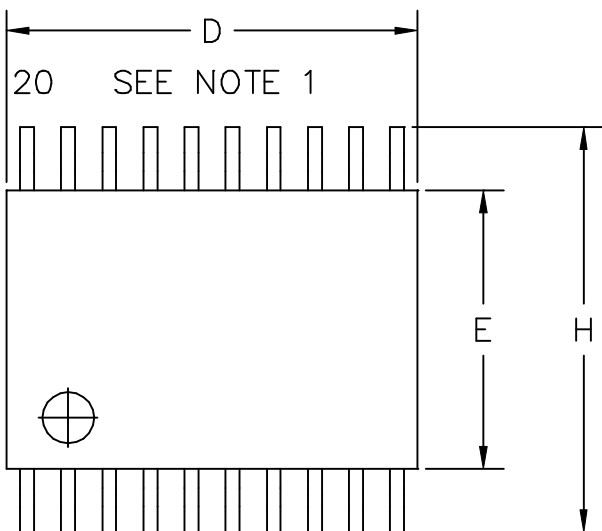
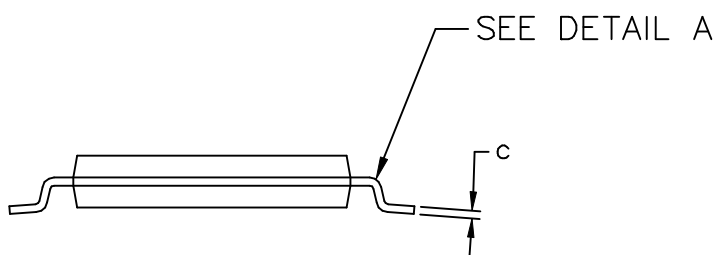
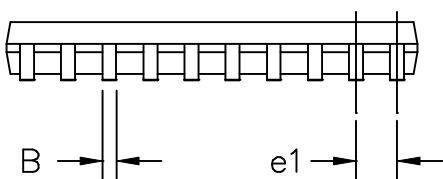




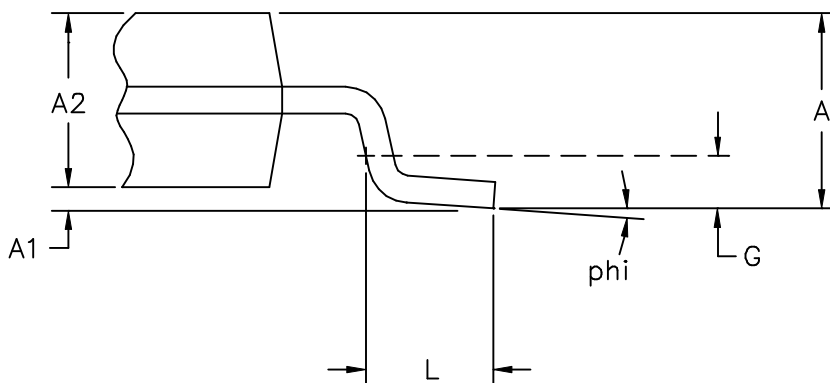
1

NOTES:

1. DIMENSION "D" INCLUDES MOLD
MISSMATCH, FLASH, AND PROTRUSIONS.



DIM	MIN	MAX
A	—	1.10
A1	0.05	—
A2	0.75	1.05
c	0.09	0.18
phi	0°	8°
L	0.50	0.70
e1	0.65 BSC	
B	0.18	0.30
D	6.40	6.90
E	4.40 NOM	
G	0.25 REF	
H	6.25	6.55



DETAIL A

DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE	 Dallas Semiconductor			
DOC. CONTROL:						
ENGR. MGR:			TITLE MARKETING OUTLINE, 20 LD. TSSOP, 4.4 MM BODY			
MFG. ENGR:						
CHECKED BY:						
DRAWN BY:			SIZE A	FSCM NO	PART NO.	REV B
DO NOT SCALE DWG.			SCALE N/A		SHEET 1 OF 1	